

## Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Green Device Available
- ESD Protected 2KV Embedded

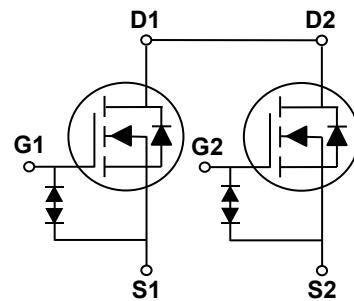
## Product Summary



$V_{DS}$	20	V
$I_D$	10	A
$R_{DS(ON)}$ (at $V_{GS}=4.5V$ )	11	mΩ
$R_{DS(ON)}$ (at $V_{GS}=2.5V$ )	14	mΩ

## Applications

- Handheld Instruments
- Battery Switch



## Absolute Maximum Ratings( $T_A=25^\circ C$ , unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	$V_{DS}$	20	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	V
Continuous Drain Current <sup>1</sup>	$I_D$	10	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	30	A
Total Power Dissipation	$P_D$	1.25	W
Storage Temperature Range	$T_{STG}$	-55 to 150	°C
Operating Junction Temperature Range	$T_J$	-55 to 150	°C

## Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance Junction-Ambient <sup>1</sup>	$R_{\theta JA}$	---	100	°C/W

## 20V Common-Drain Dual N-Channel MOSFET

Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	20	---	---	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=4.5\text{V}$ , $I_D=7\text{A}$	---	10	11	$\text{m}\Omega$
		$V_{\text{GS}}=2.5\text{V}$ , $I_D=4\text{A}$	---	12	14	$\text{m}\Omega$
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D = 250\mu\text{A}$	0.5	---	1.0	V
Drain-Source Leakage Current	$I_{\text{DSS}}$	$V_{\text{DS}}=16\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
Gate-Source Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm 10\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	$\text{nA}$
Total Gate Charge	$Q_g$	$V_{\text{DS}}=10\text{V}$ , $V_{\text{GS}}=4.5\text{V}$ , $I_D=7\text{A}$	---	15	---	nC
Gate-Source Charge	$Q_{\text{gs}}$		---	3	---	
Gate-Drain Charge	$Q_{\text{gd}}$		---	4	---	
Turn-On Delay Time	$T_{\text{d}(\text{on})}$	$V_{\text{DS}}=10\text{V}$ , $V_{\text{GS}}=4.5\text{V}$ , $R_G=4.5\Omega$ , $I_D=7\text{A}$	---	0.1	---	ns
Rise Time	$T_r$		---	0.3	---	
Turn-Off Delay Time	$T_{\text{d}(\text{off})}$		---	3.4	---	
Fall Time	$T_f$		---	2.8	---	
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=10\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	940	---	pF
Output Capacitance	$C_{\text{oss}}$		---	130	---	
Reverse Transfer Capacitance	$C_{\text{rss}}$		---	120	---	

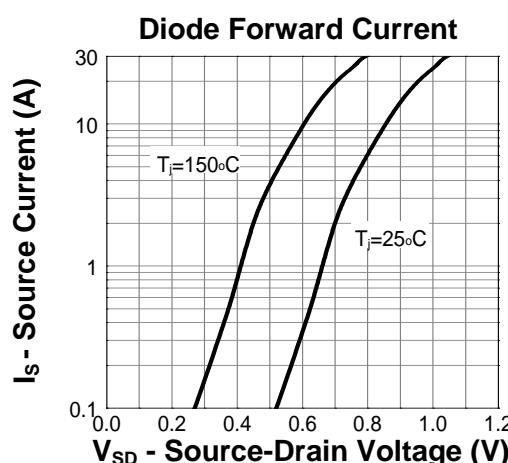
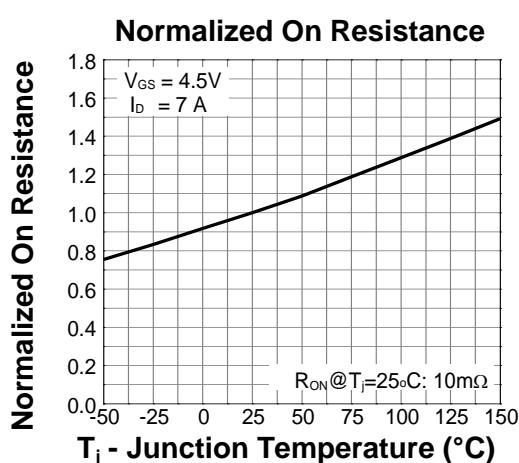
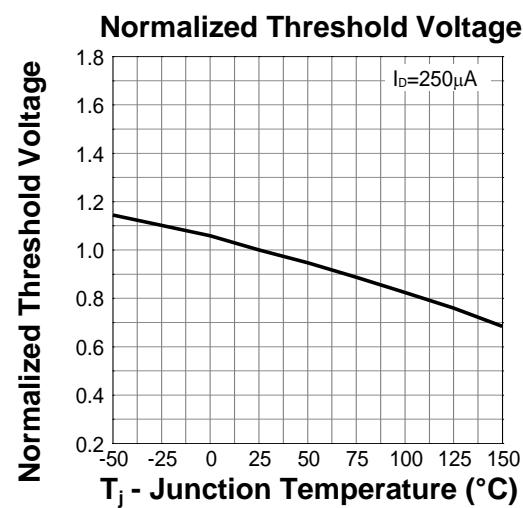
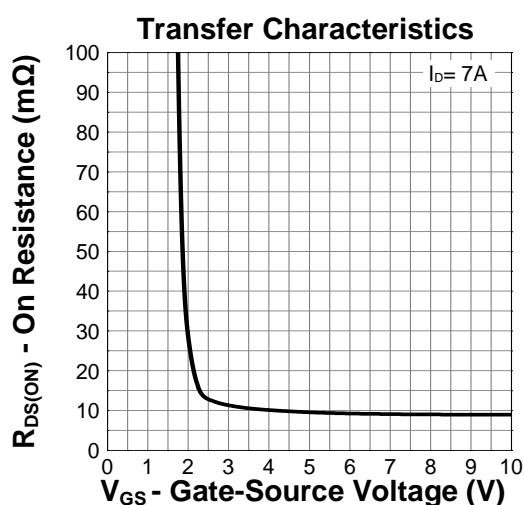
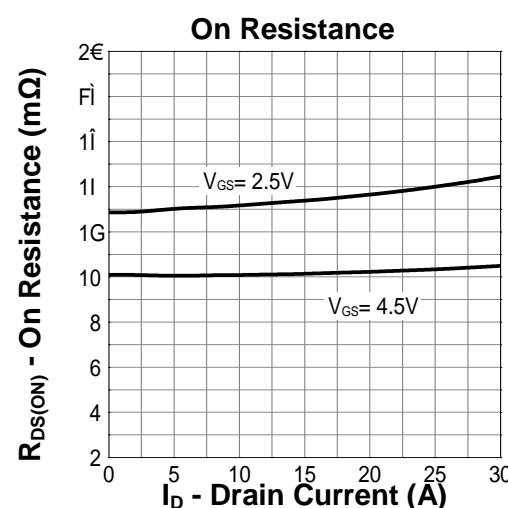
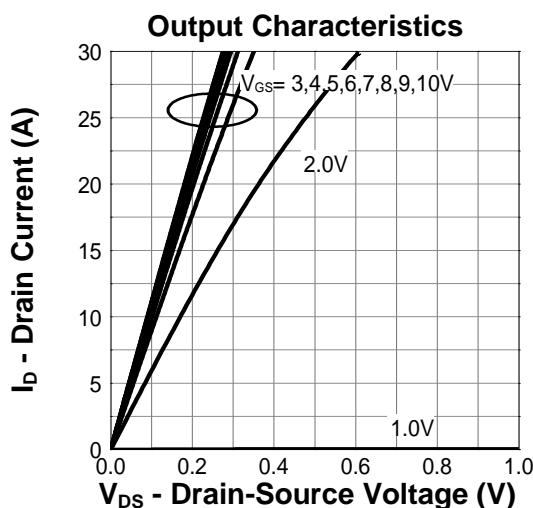
## Drain-Source Diode Characteristics

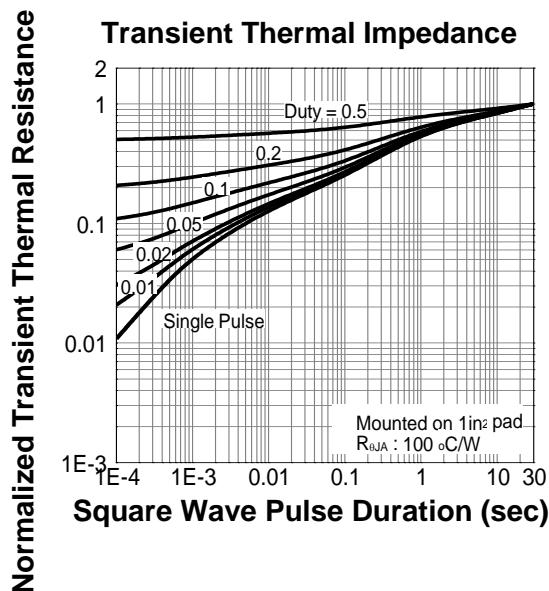
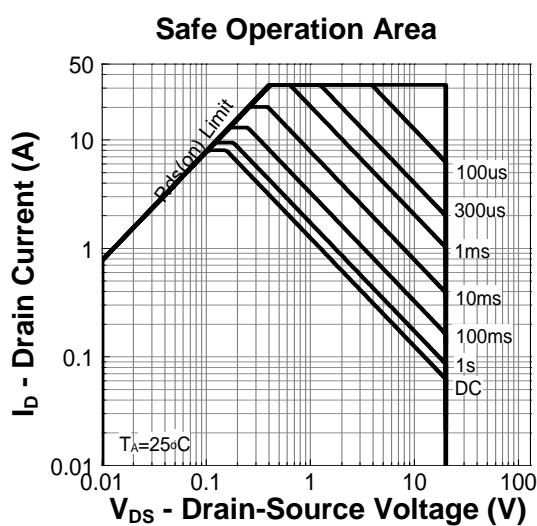
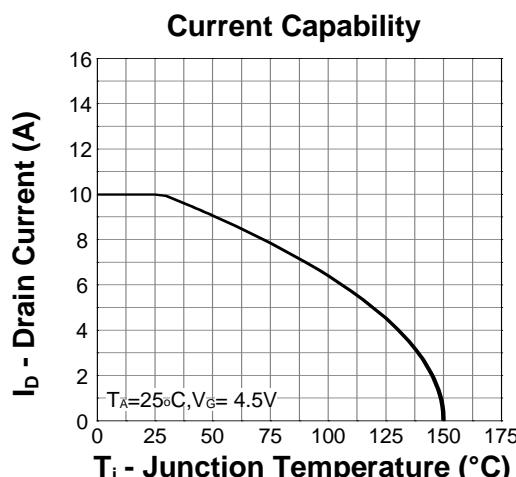
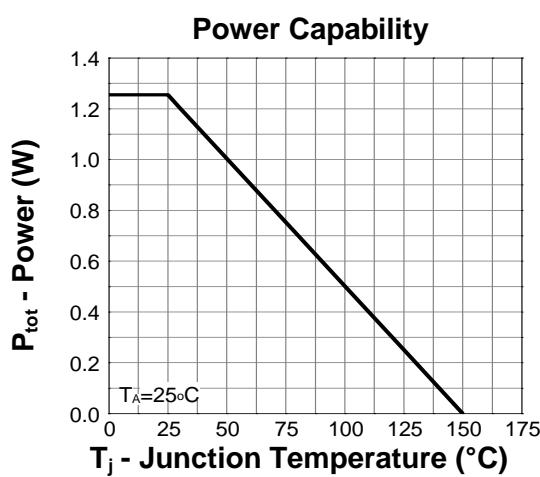
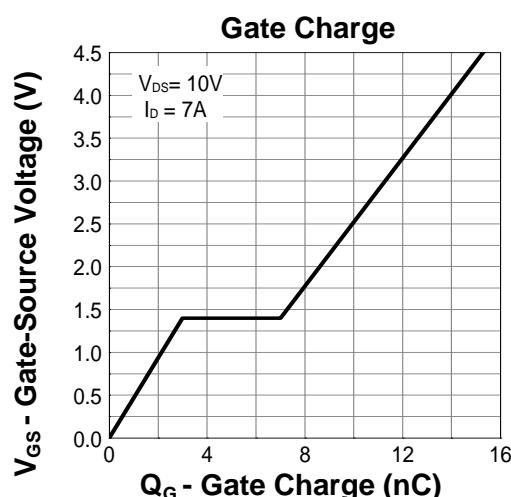
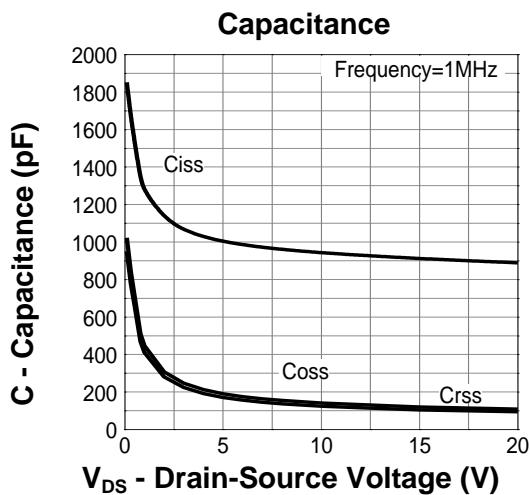
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Diode Forward Voltage <sup>2</sup>	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}$ , $I_s=7\text{A}$ , $T_J=25^\circ\text{C}$	---	0.8	1.2	V

## Note:

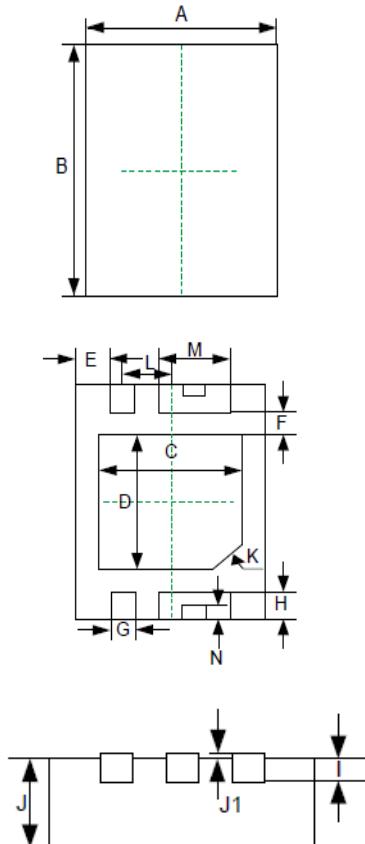
1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$

## Typical Characteristics

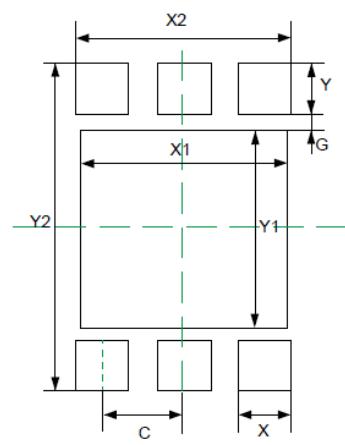




### DFN2X3-6L Package Outline Dimensions



Dim	Millimeters	
	MIN	MAX
A	1.95	2.05
B	2.95	3.05
C	1.45	1.55
D	1.65	1.75
E	0.33	0.43
F	0.25	0.35
G	0.20	0.30
H	0.35	0.45
I	0.2BSC	
J	0.527	0.577
J1	0-0.05	
K	0.3X45° BSC	
L	0.5 BSC	
M	0.70	0.80
N	0.10	0.20



Dim	Millimeters
C	0.650
G	0.150
X	0.400
X1	1.600
X2	1.700
Y	0.530
Y1	1.940
Y2	3.300